

# LNPT<sup>TM</sup> THERMOCOMP<sup>TM</sup> COMPOUND LX04015

PDXL04015

## DESCRIPTION

LNP THERMOCOMP LX04015 compound is based on Polyetheretherketone (PEEK) resin containing 15% carbon fiber. Added features of this grade include: Electrically Conductive, Easy Molding.

GENERAL INFORMATION	
Features	Electrically Conductive, Good Processability, Carbon fiber filled, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding
INDUSTRY	SUB INDUSTRY
Consumer	Commercial Appliance
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

## TYPICAL PROPERTY VALUES

Revision 20240711

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Stress, yield, 5 mm/min	200	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2	%	ISO 527
Tensile Modulus, 1 mm/min	13800	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	275	MPa	ISO 178
Flexural Strain, break, 2 mm/min	3.1	%	ISO 178
Flexural Modulus, 2 mm/min	11100	MPa	ISO 178
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, unnotched 80*10*4 +23°C	30	kJ/m <sup>2</sup>	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	5	kJ/m <sup>2</sup>	ISO 180/1A
<b>THERMAL <sup>(1)</sup></b>			
CTE, 23°C to 60°C, flow	1.E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	5.4E-05	1/°C	ISO 11359-2
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	300	°C	ISO 75/Af
<b>PHYSICAL <sup>(1)</sup></b>			
Mold Shrinkage, flow <sup>(2)</sup>	0.1 – 0.3	%	SABIC method
Density	1.34	g/cm <sup>3</sup>	ISO 1183
<b>ELECTRICAL <sup>(1)</sup></b>			
Surface Resistivity	1.E+04 – 1.E+07	Ω	ASTM D257
<b>INJECTION MOLDING <sup>(3)</sup></b>			
Drying Temperature	120 – 150	°C	

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Drying Time	4	Hrs	
Maximum Moisture Content	0.1	%	
Melt Temperature	380 – 390	°C	
Front - Zone 3 Temperature	380 – 395	°C	
Middle - Zone 2 Temperature	365 – 375	°C	
Rear - Zone 1 Temperature	350 – 360	°C	
Mold Temperature	140 – 165	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 – 100	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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